

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-288801

(43)Date of publication of application : 19.10.1999

(51)Int.Cl.

H01C 7/00
H01B 1/22
H01C 17/06

(21)Application number : 10-089016

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(22)Date of filing : 01.04.1998

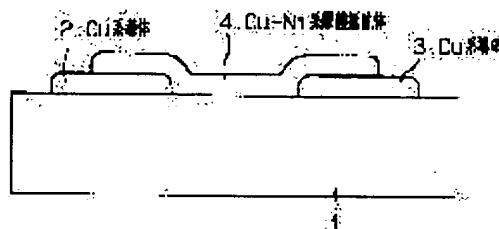
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(54) RESISTOR PASTE, FORMATION METHOD FOR THICK-FILM RESISTOR, AND MANUFACTURE OF THICK-FILM SUBSTRATE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a thick-film resistor of small temperature coefficient resistance(TRC), without using a material which adversely affects the environment such as lead.

SOLUTION: On a ceramic substrate 1, where Cu group conductors 2 and 3 are arranged, this resistor paste for which conductive powder constituting of a mixed power (Cu/Ni=60/40 to 80/20) of copper powder and nickel powder, the glass powder of 3-20 pts.wt. to the 100 pts.wt. of the conductive powder and the copper oxide powder of 1-10 pts.wt. are disposed to a vehicle, composed of organic resin and a solvent with the ratio of conductive components of 75-90 wt.% is printed. Then, it is calcined in a nitrogen atmosphere, and a thick film substrate is manufactured. For the resistor paste, the main component of glass is composed of ZnO or BaO or both and a copper oxide consists of Cu₂O or CuO or the mixture of Cu₂O and CuO. The grain diameter of the copper powder is 0.1-2 μm, the grain diameter of the nickel powder is 0.1 μm-2 μm and the grain diameter of the copper oxide is 1 μm-10 μm.



LEGAL STATUS

[Date of request for examination] 13.10.2000

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted]

registration]

[Date of final disposal for application]

[Patent number] 3559160

[Date of registration] 28.05.2004

[Number of appeal against examiner's decision of
rejection]

[Date of requesting appeal against examiner's decision
of rejection]

[Date of extinction of right]

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